

PART INFORMATION

Mfg Item Number	MC68060RC60
Mfg Item Name	PGA 206

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2007-05-04
Response Document ID	0835K00058D005A1.2
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
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Representative Title	EPP Customer Response
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URL for Additional Information	www.freescale.com

DECLARATION

EU RoHS	Yes
Pb Free	No
HalogenFree	Yes
Plating Indicator	e4
EU RoHS Exemption(s)	7c-I

MANUFACTURING

Mfg Item Number	MC68060RC60
Mfg Item Name	PGA 206
Version	ALL
Weight	25.846950
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	
Peak Processing Temperature	
Max Time at Peak Temperature	
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemptions in this part	7c-I:Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

SubPart	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	REACHPPM	REACH%
Header Assembly	23.749						g				
Header Assembly		Metals	Aluminum Oxides (Al2O3)	1344-28-1		18.902163	g	795914	79.5914	731324	73.1324
Header Assembly		Metals	Chromium, metal and alloys	7440-47-3		0.311634	g	13122	1.3122	12056	1.2056
Header Assembly		Metals	Cobalt metal and alloys	7440-48-4		0.249056	g	10487	1.0487	9635	0.9635
Header Assembly		Metals	Copper, metal and alloys	7440-50-8		0.024105	g	1015	0.1015	932	0.0932
Header Assembly		Metals	Gold, metal and alloys	7440-57-5		0.088161	g	3628	0.3628	3333	0.3333
Header Assembly		Metals	Iron, metal and alloys	7439-89-6		0.743795	g	31319	3.1319	28776	2.8776
Header Assembly		Metals	Molybdenum, metal and alloys	7439-98-7		0.063481	g	2673	0.2673	2456	0.2456
Header Assembly		Metals	Nickel, metal and alloys	7440-02-0		0.437742	g	18432	1.8432	16935	1.6935
Header Assembly		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		1.599756	g	67361	6.7361	61893	6.1893
Header Assembly		Metals	Silver, metal and alloys	7440-22-4		0.136675	g	5755	0.5755	5287	0.5287
Header Assembly		Metals	Tungsten, metal and alloys	7440-33-7		1.194432	g	50294	5.0294	46211	4.6211
Cap/Cover	1.8488						g				
Cap/Cover		Metals	Cobalt metal and alloys	7440-48-4		0.27732	g	150000	15	10729	1.0729
Cap/Cover		Metals	Gold, metal and alloys	7440-57-5		0.073952	g	40000	4	2861	0.2861
Cap/Cover		Metals	Iron, metal and alloys	7439-89-6		0.9244	g	500000	50	35764	3.5764
Cap/Cover		Metals	Nickel, metal and alloys	7440-02-0		0.55464	g	300000	30	21458	2.1458
Cap/Cover		Metals	Tin, metal and alloys	7440-31-5		0.018488	g	10000	1	715	0.0715
Epoxy Die Attach	0.0784				7c-1		g				
Epoxy Die Attach		Metals	Lead monoxide	1317-36-8		0.00162	g	20661	2.0661	62	0.0062
Epoxy Die Attach		Solvents, additives, and other materials	Other organic Silicon Compounds	-		0.006479	g	82645	8.2645	250	0.025
Epoxy Die Attach		Metals	Silver, metal and alloys	7440-22-4		0.064793	g	826447	82.6447	2506	0.2506
Epoxy Die Attach		Metals	Silver (I) oxide	20667-12-3		0.00324	g	41322	4.1322	125	0.0125
Epoxy Die Attach		Metals	Tellurium in Glass fnt	7446-07-3		0.000648	g	8264	0.8264	25	0.0025
Epoxy Die Attach		Metals	Vanadium (V) oxide	1314-62-1		0.00162	g	20661	2.0661	62	0.0062
Bonding Wire	0.001						g				
Bonding Wire		Metals	Aluminum, metal and alloys	7429-90-5		0.001	g	1000000	100	38	0.0038
Silicon Semiconductor Die	0.16975						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances(<5%)	-		0.003395	g	20000	2	131	0.0131
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.166355	g	980000	98	6436	0.6436

LINKS

MCD LINK

Freescale website <http://www.freescale.com>

GENERAL ENVIRONMENTAL COMPLIANCE LINKS

RoHS signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf

China RoHS <http://www.freescale.com/chinarohs>

REACH signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf

ELV signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf

Conflict Minerals statement http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf

FREESCALE ENVIRONMENTAL INFORMATION

EPP website <http://www.freescale.com/epp>

FAQ http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ

Technical Service Request https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod

LINKS TO BLANK IPC1752 FORMS

Blank IPC1752 v0.9 Form http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v0.9_MCD_Template.pdf

Blank IPC1752 v1.1 Form http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/MC68060RC60_IPC1752_v09.xml

http://www.freescale.com/mcdfs/MC68060RC60_IPC1752_v11.xml

http://www.freescale.com/mcdfs/MC68060RC60_IPC1752A.xml